

Large scale characterization and quality assurance tests for CALICE AHCAL "engineering prototype"

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ICASIPM

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AIDA²⁰²⁰



High Granular Calorimeters

- International Linear Collider (ILC):

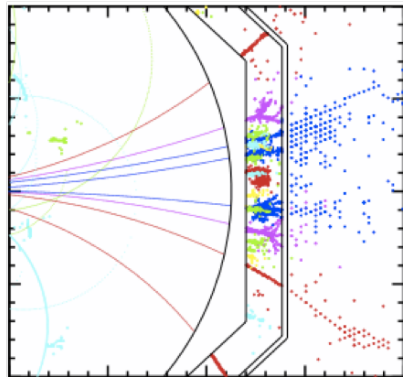
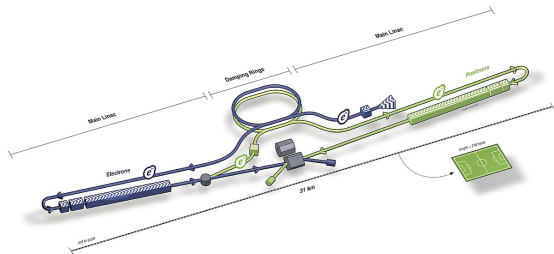
- Under discussion in Japan
- $\sqrt{s} = 250\text{--}500$ GeV, up-gradable to 1 TeV
- 31 km long, superconductive RF cavities

- High granular calorimeters:

- Motivated by requirements from precision physics programs at future lepton colliders
- Prerequisite for Particle Flow reconstruction

- Particle Flow Reconstruction:

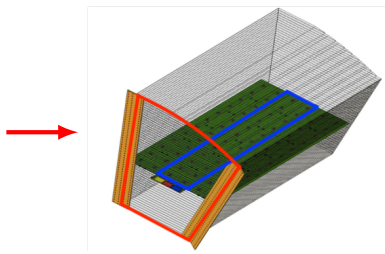
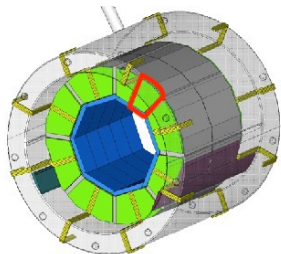
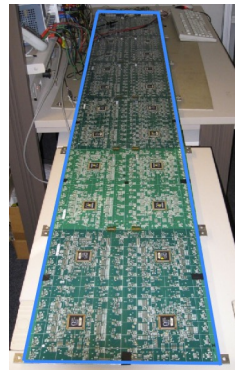
- Aim to improve the jet energy resolution
- Connecting information from all sub-detectors
 - Charged particles measured in Tracker
 - Photons measured in Electromagnetic Calorimeter (ECAL)
 - Neutral hadrons measured in Hadronic Calorimeter (HCAL)
- Separate energy depositions from close-by particles: high granularity is essential



M.A. Thomson: NIMA 611 (2009) 25-40

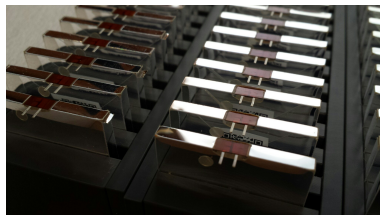
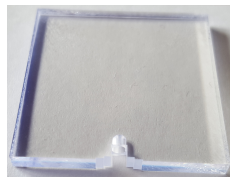
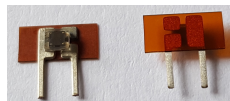
Scintillator based hadronic calorimeter (AHCAL)

- Sandwich calorimeter based on scintillator tiles ($3 \times 3 \text{ cm}^2$) readout using SiPMs
- Fully integrated electronics
- HCAL Base Unit (HBU): $36 \times 36 \text{ cm}^2$, 144 channels, 4 ASICs
- High granularity: **8M** channels
- Technological prototype: demonstrate **scalability** to full detector



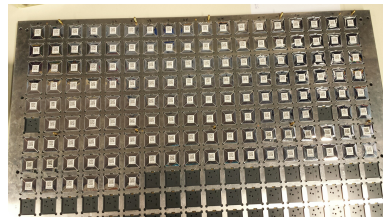
Old tile design

- physical prototype since 2006
- Channel Design (2014):
 - Complex tile design
 - Individual tile warpping (laser cutted, semi-automatic assembly)
 - Plastic scintillator machined manually
 - SiPMs soldered to pins and glued to kapton
 - Sensor glued to Tile
- QA:
 - Test cell (Tile+SiPM) before assembly on HBU
 - Full SiPM characterization
 - Light yield estimation for fixed over voltage
- Production flow:
 - SiPM soldered and glued to Kapton
 - Scintillator machining (manual)
 - Tile wrapping
 - Sensor glued to tile (manually)
 - QA test
 - Detector solder to HBU (manually)

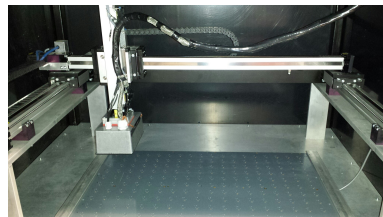


Old Tile tester

- Tester plate:
 - Can hold up to 220 Tiles
 - Dedicated connectors for the SiPMs pins
 - Dedicated holes for laser input
- Tester head:
 - Assembled on XYZ stage
 - Include 12 fibers (measure 12 channels simultaneously)
 - Include integrated electronic (Klaus ASIC)
 - Connection to SiPMs with spring loaded pins
 - HV supply
- Output:
 - Breakdown voltage
 - LY at a fixed over voltage
 - DCR



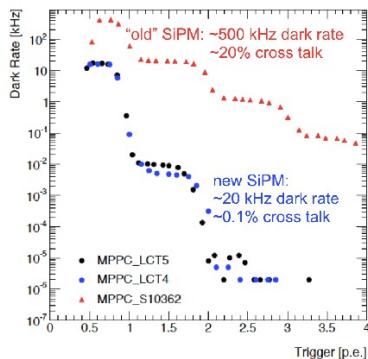
Tester plate



moving stage with tester head

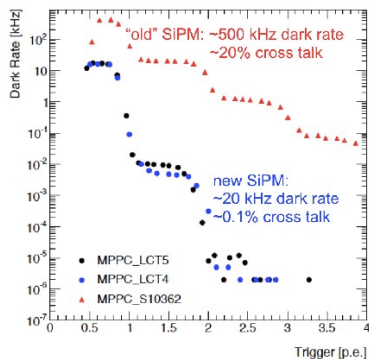
Engineering prototype - new design

- Engineering prototype goals:
 - Large scale - 24,000 channels
 - Scalability to full detector
 - Automatized production!
 - Improvement in uniformity and performance with compare to the physics prototype
- New generation of industrial SiPM:
 - Dramatically reduced DCR
 - Increase PDE
 - Better signal-to-noise ratio
 - After-pulses and inter-pixel cross-talk rates reduced
 - Noise rate decreases quickly with threshold leads to more stable operation
 - Excellent uniformity (operating voltage, gain) → simplified calibration
 - High over-voltage operation → reduced temperature sensitivity



Engineering prototype - new design

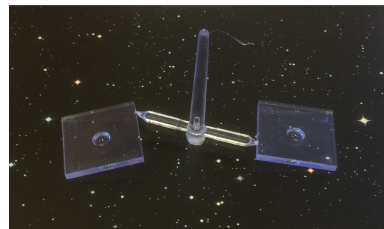
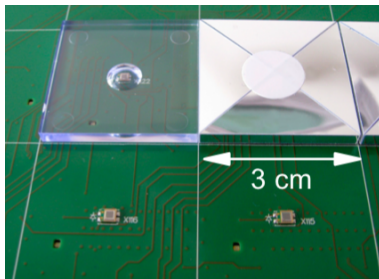
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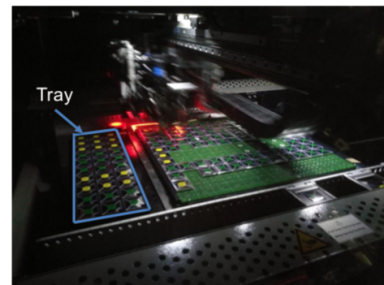
Allow re-design of tile-SiPM concept

New detector design

- SMD SiPM \rightarrow directly soldered on the HBU
- Simpler tile design
 \rightarrow allow injecting moulding (tile/min, Lebedev Physics Institute)
- Tile wrapping using fully automatic machine (Uni. Hamburg)
- Tile assembly using pick and place machine (Uni. Mainz)



Injected mould tiles



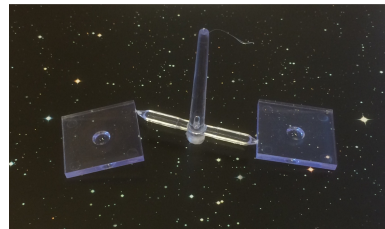
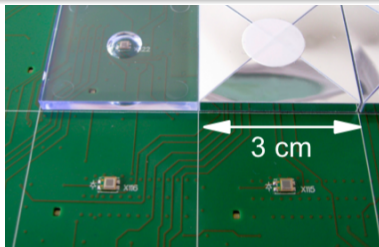
Automatic placing of tiles

New detector design

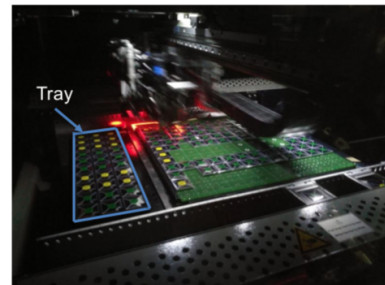
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QA tests in two steps

- SiPM QA before soldering
- Test tile+SiPM after assembly



Injected mould tiles



Automatic placing of tiles

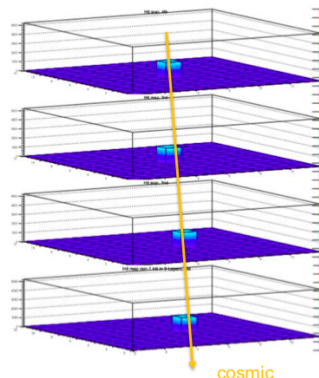
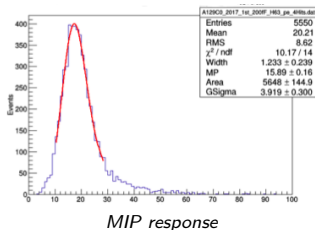
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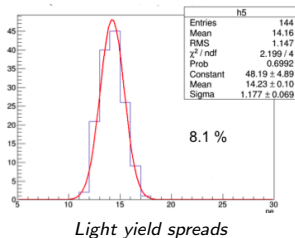
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**Stable
temperature!**



Cosmic setup



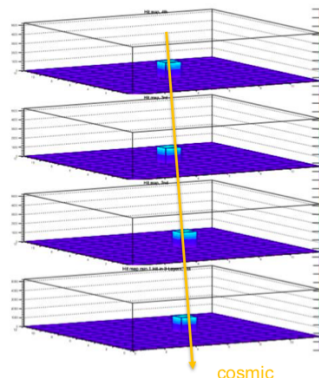
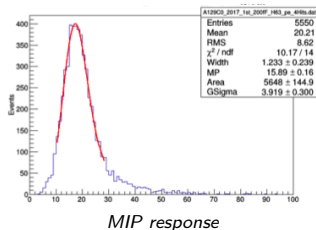
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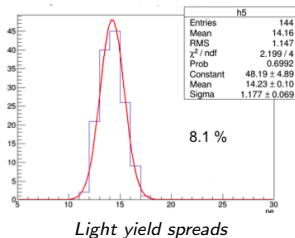
QA tests in two steps

- SiPM QA before soldering (Heidelberg University)
- Test Tile+SiPM after assembly

**Stable
temperature!**



Cosmic setup



SiPM QA requirements

- Setup requirements:
 - Readout SMD SiPM without soldering
 - **Scalable** design
 - **Fast** testing
- SiPM requirements (@25°C, 5 V OV):
 - ~ 2700 pixels, pixel size $25\ \mu m$
 - $DCR < 500\text{ kHz}$
 - Cross-talk $< 3\%$
 - $PDE\ (@420\text{ nm}) > 20\%$
 - $Gain > 3 \times 10^5$
 - $dV/dT < 1\%$ of excess bias voltage ($\sim 50\text{ mV/k}$)
 - Breakdown voltage min-max spread 200 mV within a batch
 - For quality assurance: test a small sample (4% from each batch)
- Accept maximum 1 outlier from each batch of 600 Sensors

SiPM QA setup

- System components:

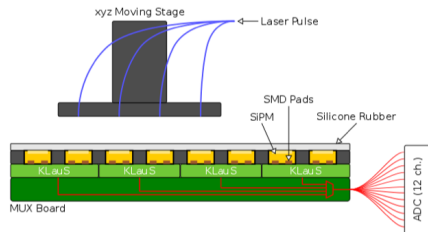
- Laser head with 12 optical fibers
- Base plate:
 - Up to 144 SMD SiPMs
 - RO - 12 KlauS2 ASICs
 - Multiplexing of KlauS2 output signals to 12 channels ADC
- Fiber/SiPMs spacing compatible to HBU

- Advantages:

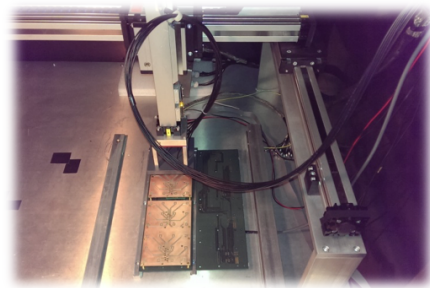
- Measure 48 SiPMs in ~ 8 min
- Can be used both for SMD SiPM QA or on equipped HBU
- Modular - can be easily scaled up the no. of channels

- Disadvantage:

- Manually placed the SiPMs
- Need to take SiPMs out of the sealed tape

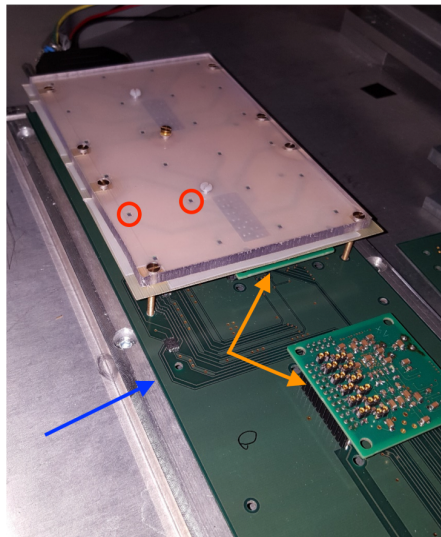


SMD SiPM schematic view



Single base plate

- 24 SiPMs
- Multiplex PCB
- 2 Klaus ASICs
- Current prototype have 2 module (up to 48 SiPMs)
- The design is modular and can be scale up if needed for mass production



SMD SiPM base plate

Measurement procedure

Measurement:

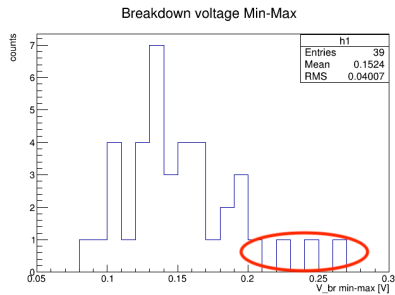
- Using low intensity light spectra
- The setup is inside an oven with constant temperature of 25°C
- Measure the SPS spectrum for voltage range of 1 V to 7 V above breakdown (Hamamatsu datasheet) at step size of 0.1 V
- For the sample measured during night re-measure for temperatures (10,15,20,25,30,35,40°C)

Analysis:

- Extract from each SPS spectrum the gain using FFT
- Extract the breakdown voltage for each temperature and SiPM from linear fit of gain vs. voltage
- Estimate the DCR from SPS using Poisson statistics:
$$DCR = -\ln\left(\frac{N_0}{N_{tot}}/\Delta t\right) \quad (1)$$
- Estimate CT upper limit from the DCR spectrum
- extract for each SiPM the temperature coefficient from linear fit of the breakdown voltage vs. temperature (for available samples)

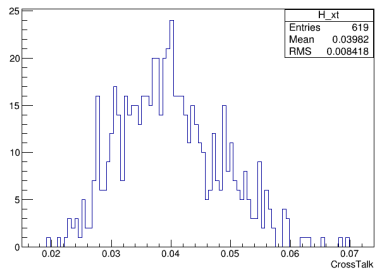
* the gain is measured in arbitrary units $\rightarrow 13 \sim 3 \times 10^5$ (the requirement)

Example results



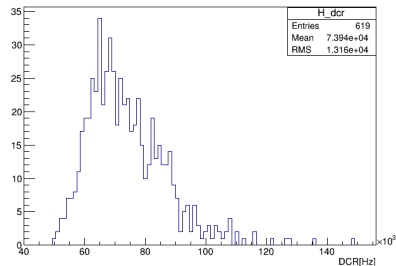
breakdown voltage min-max spread

xt @ vbr_mean+5

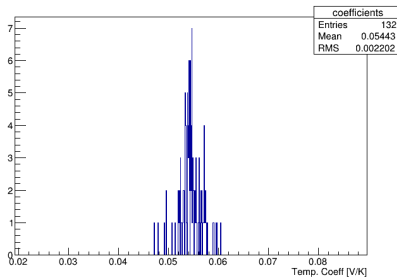


Cross-talk spread

dcr @ vbr_mean+5



DCR spread



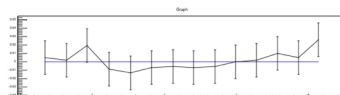
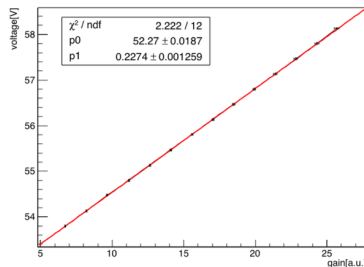
Temperature coefficient spread

Results

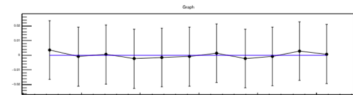
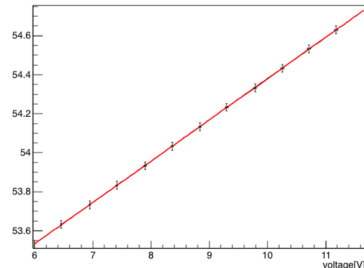
- DCR < 500 KHz **OK!**
- Gain $> 3 \times 10^5$ **OK!**
- $dV/dT < 1\%$ **OK!**
- V_{bd} spread min-max within a batch 200 mV **OK!** (only 4 outlier)
- Cross-talk $< 3\%$ **OK**
 - include some after-pluses
 - due to much lower DCR can tolerate increase in CT
- PDE (@420 nm) $> 20\%$ - didn't measure yet (difficult without soldering)

Issues

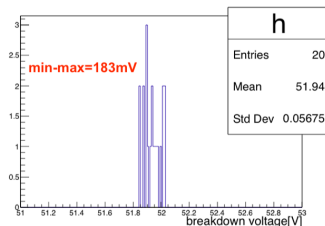
- Temperature control
- Light tight
- Non-linearity
 - Systematic in all
 - Residual < 10 mV
 - Possible voltage drop
- Not biasing the spread



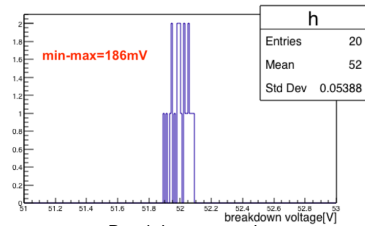
Example Voltage Vs. Gain full range



Example Voltage Vs. Gain small range



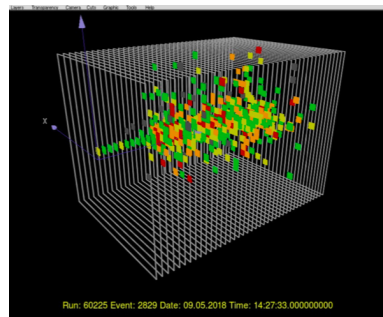
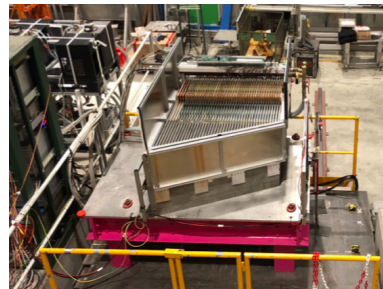
Breakdown voltage spread



Breakdown spread

Summary

- A large scale engineering prototype was build this year (24k channels)
- New test benches for QA of SMD SiPMs were designed
- Test benches are easily scaled up
- Fast SiPM characterization (~ 10 sec per SiPM)
- All SiPM batches passed the requirements
- Good uniformity in SiPM parameters observed
 - Will allow to test less SiPM in the future
- Small non linearity in gain curves didn't bias the spread measurement
- For large scale version, an active cooling will be designed



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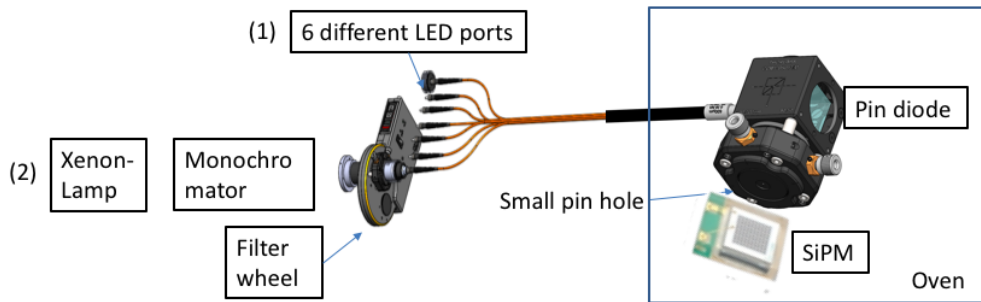
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AIDA 2020

backup Slides

PDE setup



Work principle:

